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## (54) ADHESIVE SILICONE COMPOSITION FOR HEAT RADIATION MEMBER

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a heat radiation member that has excellent heat radiation performance by compounding a large amount of thermally conductive filler and reducing the interfacial contact heat resistance by making the surface adherent.

**SOLUTION:** The adhesive silicone composition for heat radiation members comprises (A) 100 pts.wt. of a curable silicone adhesive including an organopolysiloxane of (a) R13SiO1/2 unit (wherein R1 is independently a 1-6C monovalent hydrocarbon group other than alkenyl) and SiO2 unit where the molar ratio of R13SiO1/2 unit to SiO2 unit is 0.6 to 1.7; (B) 500 to 3,000 pts.wt. of thermally conductive filler and (C) 0.1 to 50 pts.wt. of an organosilane represented by general formula (1) R2aR3bSi(OR4)4-a-b (1) (wherein R2 is a 6-15C monovalent alkyl group; R3 is an unsubstituted or substituted 1-8C monovalent hydrocarbon group; R4 is independently a 1-6C monovalent hydrocarbon group; a is an integer of 1 to 3; b is 0 or an integer of 1 or 2; the sum of a+b is an integer of 1-3).

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